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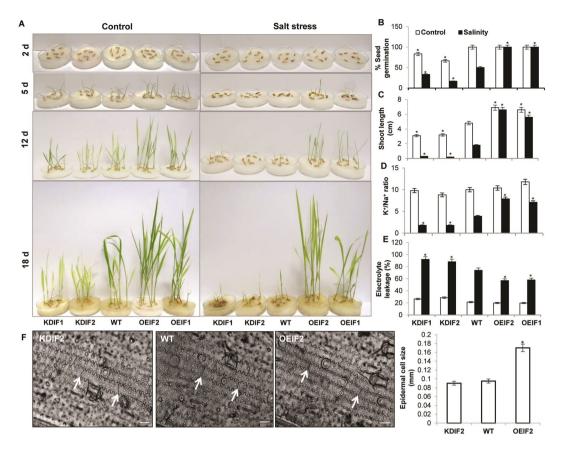
OPEN Author Correction: Rice intermediate filament, OsIF, stabilizes photosynthetic machinery and yield under salinity and heat stress

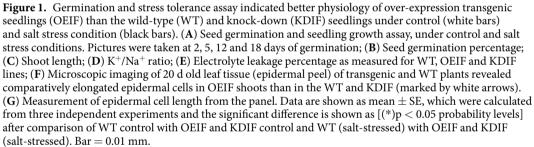
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Correction to: Scientific Reports https://doi.org/10.1038/s41598-018-22131-0, published online 06 March 2018

In Figure 3A, the image taken at 5 days of germination under salt stress conditions is incorrect. The correct Figure 3 appears below as Figure 1.

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(satt-stressed): Dat = 0.01 mm.

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